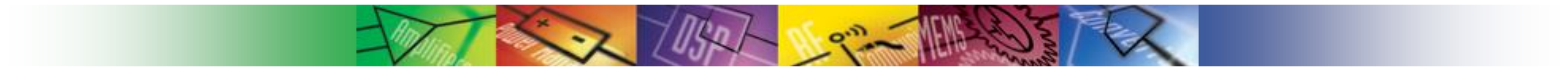

Product / Package Information

Package	LFCSP_SS
Body Size (mm)	4 X 4 X 1.45 (2.4 EP)
Lead Count	12
Terminal Finish	100 Sn
MS Number	MS012736B

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes, except Lead (Pb)
**contains Lead (Pb) > 0.1% or 1000ppm of the overall product*	
Last Updated	19-Jul-19

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.86E-02	93.70	937000	48.86	488562
Thermosets	Epoxy resin	Proprietary	9.15E-04	3.00	30000	1.56	15642
Thermosets	Phenol resin	Proprietary	9.15E-04	3.00	30000	1.56	15642
Other inorganic materials	Carbon black	1333-86-4	9.15E-05	0.30	3000	0.16	1564
Subtotal			3.05E-02	100.00	1000000	52.14	521411

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.66 E-02	97.50	975000	28.39	283897
Copper & its alloys	Iron	7439-89-6	4.00 E-04	2.35	23500	0.68	6843
Copper & its alloys	Zinc	7440-66-6	2.04 E-05	0.12	1200	0.03	349
Copper & its alloys	Phosphorus	7723-14-0	5.11 E-06	0.03	300	0.01	87
Subtotal			1.70 E-02	100.00	1000000	29.12	291176

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.83 E-04	100.0	1000000	0.31	3130

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.37 E-04	100.0	1000000	0.41	4051

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.83 E-04	99.0	990000	0.31	3135
Precious metals	Palladium	7440-05-3	1.85 E-06	1.00	10000	0.003	32
Subtotal			1.85 E-04	100.0	1000000	0.32	3167

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.10 E-03	100.0	1000000	12.13	121294

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	1.62 E-03	50	500000	2.76	27617
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	1.45 E-03	45	450000	2.49	24855
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	1.62 E-04	5	50000	0.28	2762
Subtotal			3.23 E-03	100.0	1000000	5.52	55234

Glass Cap

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Glass Cap	Lead borosilicate glass	65997-17-3	1.89 E-05	60.00	600000	0.0322	322
	Terpineol	8006-39-1	7.85 E-07	2.50	25000	0.0013	13
	Trimethyl Pentanediol Monoisobutyrate	25265-77-4	9.43 E-06	30.00	300000	0.0161	161
	Aluminosilicate glass	65997-17-3	2.36 E-06	7.50	75000	0.0040	40
Subtotal			3.14 E-05	100.00	1000000	0.05	537

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.85 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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